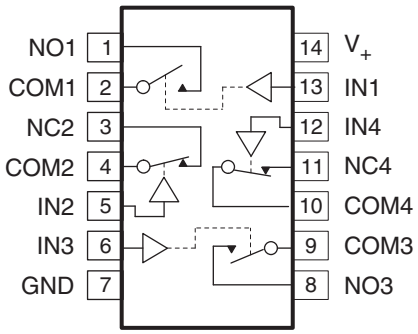
LOW ON-STATE RESISTANCE QUAD SPST CMOS ANALOG SWITCHES

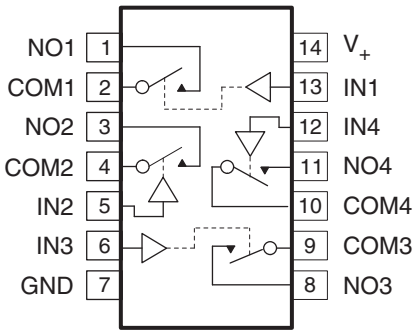
FEATURES

- 2-V to 12-V Single-Supply Operation
- Specified ON-State Resistance:
  - 15 Ω Max With 12-V Supply
  - 20 Ω Max With 5-V Supply
  - 50 Ω Max With 3.3-V Supply
- R_{DSON} Matching
  - 2.5 Ω (Max) at 12 V
  - 3 Ω (Max) at 5 V
  - 3.5 Ω (Max) at 3.3 V
- Specified Low OFF-Leakage Currents:
  - 1 nA at 25°C
  - 10 nA at 85°C
- Specified Low ON-Leakage Currents:
  - 1 nA at 25°C
  - 10 nA at 85°C
- Low Charge Injection: 11.5 pC (12-V Supply)
- Fast Switching Speed: t_{ON} = 80 ns, t_{OFF} = 50 ns (12-V Supply)
- Break-Before-Make Operation ($t_{ON} > t_{OFF}$)
- TTL/CMOS-Logic Compatible With 5-V Supply
- Available in TSSOP-14 Package, SOIC-14

D OR PW PACKAGE...TS12A44513
(TOP VIEW)



D OR PW PACKAGE...TS12A44514
(TOP VIEW)



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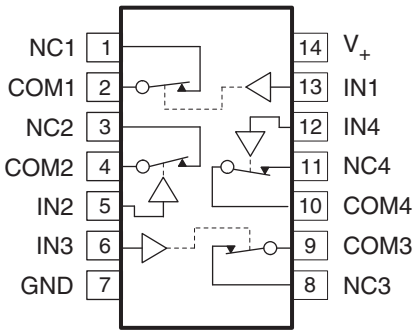

DESCRIPTION/ORDERING INFORMATION

The TS12A44513/TS12A44514/TS12A44515 are quad single pole/single throw (SPST), low-voltage / wide range, single-supply CMOS analog switches, with very low switch ON-state resistance. The TS12A44513 has two switches normally closed (NC) and two switches normally open (NO), the TS12A44514 switches are normally open (NO), the TS12A44515 switches are normally closed (NC).

These CMOS switches can operate continuously with a single supply between 2 V and 12 V. Each switch can handle rail-to-rail analog signals. The OFF-leakage current maximum is only 1 nA at 25°C or 10 nA at 85°C.

All digital inputs have 0.8-V to 2.4-V logic thresholds, ensuring TTL/CMOS-logic compatibility when using a 5-V supply.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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ORDERING INFORMATION

T_A	PACKAGE(1)(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – D	Reel of 2500	TS12A44513DR	TS12A44513
		Reel of 2500	TS12A44514DR	TS12A44514
		Reel of 2500	TS12A44515DR	TS12A44515
	TSSOP – PW	Reel of 2000	TS12A44513PWR	YD4513
		Reel of 2000	TS12A44514PWR	YD4514
		Reel of 2000	TS12A44515PWR	YD4515

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

ABSOLUTE MINIMUM AND MAXIMUM RATINGS(1)(2)

voltages referenced to GND

				MIN	MAX	UNIT
V_+	Supply voltage range			–0.3	13	V
V_{NC} V_{NO} V_{COM}	Analog voltage range(3)			–0.3	V_+ + 0.3	V
I_{NC} I_{NO} I_{COM}	Analog Current range			-20	20	mA
	Continuous current into any terminal				±20	mA
	Peak current, NO or COM (pulsed at 1 ms, 10% duty cycle)				±30	mA
	ESD per method 3015.7				2000	V
T_A	Operating temperature range			–40	85	°C
P_D	Power dissipation	Mounted on JEDEC 4-layer board (JESD 51-7), No airflow, T_A = 25°C, T_J = 125°C	D package		1.15	W
			PW package		0.88	
T_{stg}	Storage temperature range			–65	150	°C
	Lead temperature (soldering, 10 s)				300	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
(3) Voltages exceeding V_+ or GND on any signal terminal are clamped by internal diodes. Limit forward-diode current to maximum current rating.

THERMAL IMPEDANCE

					UNIT
θ_{JA}	Thermal impedance, junction to free air	Mounted on JEDEC 1-layer board (JESD 51-3), No airflow	D package	133	°C/W
			PW package	167	
		Mounted on JEDEC 4-layer board (JESD 51-7), No airflow	D package	86	
			PW package	112	

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ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY(1)

V_+ = 4.5 V to 5.5 V, V_{INH} = 2.4 V, V_{INL} = 0.8 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	T_A	MIN	TYP(2)	MAX	UNIT
Analog Switch							
Analog signal range	V_{COM}, V_{NO}, V_{NC}			0		V_+	V
ON-state resistance	r_{on}	V_+ = 4.5 V, V_{COM} = 3.5 V, I_{COM} = 1 mA	25°C		12	20	Ω
			Full			30	
ON-state resistance flatness	$r_{on(flat)}$	V_{COM} = 1 V, 2 V, 3 V, I_{COM} = 1 mA	25°C		1	3	Ω
			Full			4	
ON-state resistance matching between channels(3)	Δr_{on}	V_+ = 4.5 V, I_{COM} = 5 mA, V_{NO} or V_{NC} = 3 V	25°C			3	Ω
			T_{MIN} to T_{MAX}			4	
NO, NC OFF leakage current(4)	$I_{NO(OFF)}$, $I_{NC(OFF)}$	V_+ = 5.5 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 4.5 V	25°C			1	nA
			Full			10	
COM OFF leakage current(4)	$I_{COM(OFF)}$	V_+ = 5.5 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 4.5 V	25°C			1	nA
			Full			10	
COM ON leakage current(4)	$I_{COM(ON)}$	V_+ = 5.5 V, V_{COM} = 4.5 V, V_{NO} or V_{NC} = 4.5 V	25°C			1	nA
			Full			10	
Digital Control Input (IN)							
Input logic high	V_{IH}		Full	2.4		V_+	V
Input logic low	V_{IL}		Full	0		0.8	V
Input leakage current	I_{IH}, I_{IL}	V_{IN} = V_+, 0 V	Full			0.01	µA
Dynamic							
Turn-on time	t_{ON}	see Figure 6	25°C		45	100	ns
			Full			125	
Turn-off time	t_{OFF}	see Figure 6	25°C		35	50	ns
			Full			70	
Charge injection(5)	Q_C	C_L = 1 nF, V_{NO} = 0 V, R_S = 0 Ω, See Figure 5	25°C		–1.5		pC
NO, NC OFF capacitance	$C_{NO(OFF)}$, $C_{NC(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM OFF capacitance	$C_{COM(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM ON capacitance	$C_{COM(ON)}$	f = 1 MHz, See Figure 8	25°C		19		pF
Digital input capacitance	C_I	V_{IN} = V_+, 0 V	25°C		2		pF
Bandwidth	BW	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		530		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		–94		dB
Total harmonic distortion	THD	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		0.09		%
Supply							
V_+ supply current	I_+	V_{IN} = 0 V or V_+	25°C			0.05	µA
			Full			0.1	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) Typical values are at T_A = 25°C.
(3) $\Delta r_{ON} = r_{ON(MAX)} - r_{ON(MIN)}$
(4) Leakage parameters are 100% tested at maximum-rated hot operating temperature, and are ensured by correlation at 25°C.
(5) Specified by design, not production tested

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ELECTRICAL CHARACTERISTICS FOR 12-V SUPPLY(1)

V_+ = 11.4 V to 12.6 V, V_{INH} = 5 V, V_{INL} = 0.8 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	T_A	MIN	TYP(2)	MAX	UNIT
Analog Switch							
Analog signal range	V_{COM}, V_{NO}, V_{NC}			0		V_+	V
ON-state resistance	r_{on}	V_+ = 11.4 V, V_{COM} = 10 V, I_{COM} = 1 mA	25°C		6.5	10	Ω
			Full			15	
ON-state resistance flatness	$r_{on(flat)}$	V_+ = 11.4 V, V_{COM} = 2 V, 5 V, 10 V, I_{COM} = 1 mA	25°C		1.5	3	Ω
			Full			4	
ON-state resistance matching between channels(3)	Δr_{on}	V_+ = 11.4 V, I_{COM} = 5 mA, V_{NO} or V_{NC} = 10 V	25°C			2.5	Ω
			T_{MIN} to T_{MAX}			3	
NO, NC OFF leakage current(4)	$I_{NO(OFF)}$, $I_{NC(OFF)}$	V_+ = 12.6 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 10 V	25°C			1	nA
			Full			10	
COM OFF leakage current(4)	$I_{COM(OFF)}$	V_+ = 12.6 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 10 V	25°C			1	nA
			Full			10	
COM ON leakage current(4)	$I_{COM(ON)}$	V_+ = 12.6 V, V_{COM} = 10 V, V_{NO} or V_{NC} = 10 V	25°C			1	nA
			Full			10	
Digital Control Input (IN)							
Input logic high	V_{IH}		Full	5		V_+	V
Input logic low	V_{IL}		Full	0		0.8	V
Input leakage current	I_{IH}, I_{IL}	V_{IN} = V_+, 0 V	Full			0.001	µA
Dynamic							
Turn-on time	t_{ON}	See Figure 6	25°C		25	75	ns
			Full			80	
Turn-off time	t_{OFF}	See Figure 6	25°C		20	45	ns
			Full			50	
Charge injection(5)	Q_C	C_L = 1 nF, V_{NO} = 0 V, R_S = 0 Ω, See Figure 5	25°C		–10.5		pC
NO, NC OFF capacitance	$C_{NO(OFF)}$, $C_{NC(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM OFF capacitance	$C_{COM(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM ON capacitance	$C_{COM(ON)}$	f = 1 MHz, See Figure 8	25°C		21.5		pF
Digital input capacitance	C_I	V_{IN} = V_+, 0 V	25°C		2		pF
Bandwidth	BW	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		530		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		–95		dB
Total harmonic distortion	THD	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		0.07		%
Supply							
V_+ supply current	I_+	V_{IN} = 0 V or V_+	25°C			0.05	µA
			Full			0.2	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) Typical values are at T_A = 25°C.
(3) $\Delta r_{ON} = r_{ON(MAX)} - r_{ON(MIN)}$
(4) Leakage parameters are 100% tested at maximum-rated hot operating temperature, and are ensured by correlation at 25°C.
(5) Specified by design, not production tested

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ELECTRICAL CHARACTERISTICS FOR 3-V SUPPLY(1)

V_+ = 3 V to 3.6 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	T_A	MIN	TYP(2)	MAX	UNIT
Analog Switch							
Analog signal range	V_{COM}, V_{NO}, V_{NC}			0		V_+	V
ON-state resistance	r_{on}	V_+ = 3 V, V_{COM} = 1.5 V, I_{NO} = 1 mA,	25°C		20	40	Ω
			Full			50	
ON-state resistance flatness	$r_{on(flat)}$	V_+ = 3 V, V_{COM} = 1 V, 1.5 V, 2 V, I_{COM} = 1 mA	25°C		1	3	Ω
			Full			4	
ON-state resistance matching between channels(3)	Δr_{on}	V_+ = 2.7 V, I_{COM} = 5 mA, V_{NO} or V_{NC} = 1.5 V	25°C			3.5	Ω
			T_{MIN} to T_{MAX}			4.5	
NO, NC OFF leakage current(4)	$I_{NO(OFF)}$, $I_{NC(OFF)}$	V_+ = 3.6 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 3 V	25°C			1	nA
			Full			10	
COM OFF leakage current(4)	$I_{COM(OFF)}$	V_+ = 3.6 V, V_{COM} = 1 V, V_{NO} or V_{NC} = 3 V	25°C			1	nA
			Full			10	
COM ON leakage current(4)	$I_{COM(ON)}$	V_+ = 3.6 V, V_{COM} = 3 V, V_{NO} or V_{NC} = 3 V	25°C			1	nA
			Full			10	
Digital Control Input (IN)							
Input logic high	V_{IH}		Full	2.4		V_+	V
Input logic low	V_{IL}		Full	0		0.8	V
Input leakage current	I_{IH}, I_{IL}	V_{IN} = V_+, 0 V	Full			0.01	µA
Dynamic							
Turn-on time(5)	t_{ON}	See Figure 6	25°C		70	120	ns
			Full			175	
Turn-off time(5)	t_{OFF}	See Figure 6	25°C		50	80	ns
			Full			120	
Charge injection(5)	Q_C	C_L = 1 nF, See Figure 5	25°C		–0.5		pC
NO, NC OFF capacitance	$C_{NO(OFF)}$, $C_{NC(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM OFF capacitance	$C_{COM(OFF)}$	f = 1 MHz, See Figure 8	25°C		8		pF
COM ON capacitance	$C_{COM(ON)}$	f = 1 MHz, See Figure 8	25°C		17		pF
Digital input capacitance	C_I	V_{IN} = V_+, 0 V	25°C		2		pF
Bandwidth	BW	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		510		MHz
OFF isolation	O_{ISO}	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		–94		dB
Total harmonic distortion	THD	R_L = 50 Ω, C_L = 15 pF, V_{NO} = 1 V_{RMS}, f = 100 kHz	25°C		0.27		%
Supply							
V_+ supply current	I_+	V_{IN} = 0 V or V_+	25°C			0.03	µA
			Full			0.05	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(2) Typical values are at T_A = 25°C.
(3) $\Delta r_{ON} = r_{ON(MAX)} - r_{ON(MIN)}$
(4) Leakage parameters are 100% tested at maximum-rated hot operating temperature, and are ensured by correlation at 25°C.
(5) Specified by design, not production tested

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TYPICAL PERFORMANCE

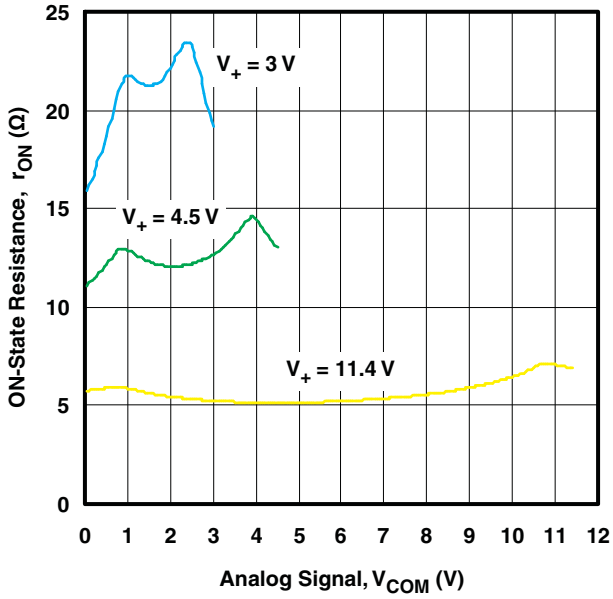

Figure 1. r_{ON} vs V_{COM} (T_A = 25°C)

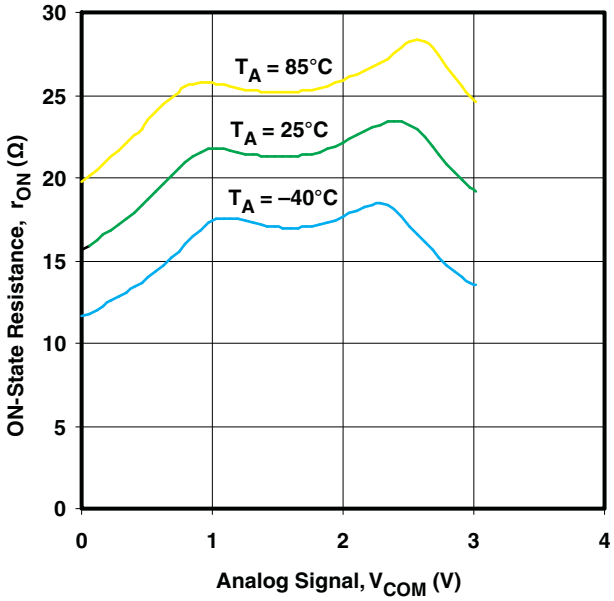

Figure 2. r_{ON} vs V_{COM} (V_+ = 3 V)

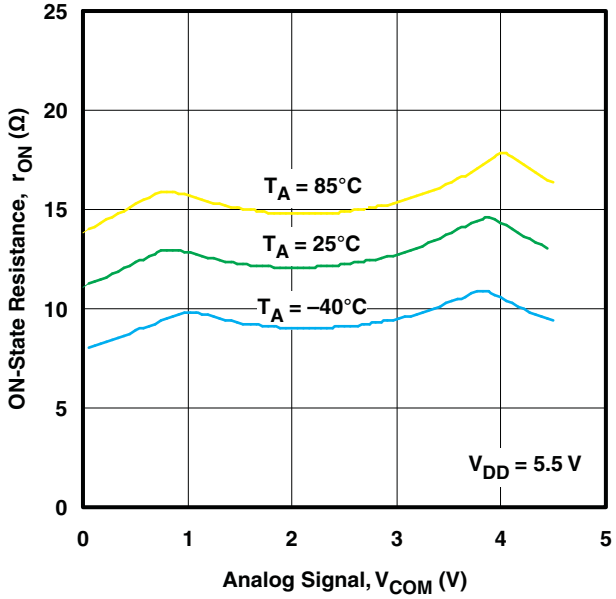

Figure 3. r_{ON} vs V_{COM} (V_+ = 4.5 V)

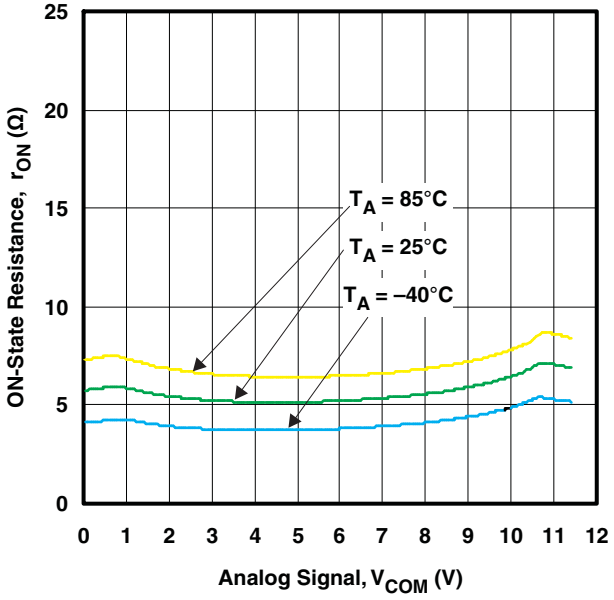

Figure 4. r_{ON} vs V_{COM} (V_+ = 11.4 V)

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PIN DESCRIPTION(1)

PIN NO.			NAME	DESCRIPTION
TS12A44513	TS12A44514	TS12A44515		
TSSOP-14				
2, 4, 9, 10	2, 4, 9, 10	2, 4, 9, 10	COM	Common
14	14	14	V_+	Power supply
5, 6, 12, 13	5, 6, 12, 13	5, 6, 12, 13	IN	Digital control to connect COM to NO or NC
7	7	7	GND	Digital ground
1, 8	1, 3, 8, 11	–	NO	Normally open
3, 11	–	1, 3, 8, 11	NC	Normally closed

(1) NO, NC, and COM pins are identical and interchangeable. Any may be considered as an input or an output; signals pass in both directions.

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APPLICATION INFORMATION

Power-Supply Considerations

The TS12A44513/TS12A44514/TS12A44515 construction is typical of most CMOS analog switches, except that they have only two supply pins: V_+ and GND. V_+ and GND drive the internal CMOS switches and set their analog voltage limits. Reverse ESD-protection diodes connected in series are internally connected between each analog-signal pin and both V_+ and GND. If an analog signal exceeds V_+ or GND, one of the diodes will be forward biased, but the other will be reverse biased preventing current flow.

Virtually all the analog leakage current comes from the ESD diodes to V_+ or GND. Although the ESD diodes on a given signal pin are identical and, therefore, fairly well balanced, they are reverse biased differently. Each is biased by either V_+ or GND and the analog signal. This means their leakages will vary as the signal varies. The difference in the two diode leakages to the V_+ and GND pins constitutes the analog-signal-path leakage current. All analog leakage current flows between each pin and one of the supply terminals, not to the other switch terminal. This is why both sides of a given switch can show leakage currents of the same or opposite polarity.

There is no connection between the analog-signal paths and V_+ or GND.

V_+ and GND also power the internal logic and logic-level translators. The logic-level translators convert the logic levels to switched V_+ and GND signals to drive the analog signal gates.

Logic-Level Thresholds

The logic-level thresholds are CMOS/TTL compatible when V_+ is 5 V. As V_+ is raised, the level threshold increases slightly. When V_+ reaches 12 V, the level threshold is about 3 V – above the TTL-specified high-level minimum of 2.8 V, but still compatible with CMOS outputs.

CAUTION:

Do not connect the TS12A44513/TS12A44514/MAS4515 V_+ to 3 V and then connect the logic-level pins to logic-level signals that operate from 5-V supply. Output levels can exceed 3 V and violate the absolute maximum ratings, damaging the part and/or external circuits.

High-Frequency Performance

In 50-Ω systems, signal response is reasonably flat up to 250 MHz (see *Typical Operating Characteristics*). Above 20 MHz, the on response has several minor peaks that are highly layout dependent. The problem is not in turning the switch on; it is turning it off. The OFF-state switch acts like a capacitor and passes higher frequencies with less attenuation. At 10 MHz, OFF isolation is about –45 dB in 50-Ω systems, decreasing (approximately 20 dB per decade) as frequency increases. Higher circuit impedances also make OFF isolation decrease. OFF isolation is about 3 dB above that of a bare IC socket, and is due entirely to capacitive coupling.

Test Circuits/Timing Diagrams

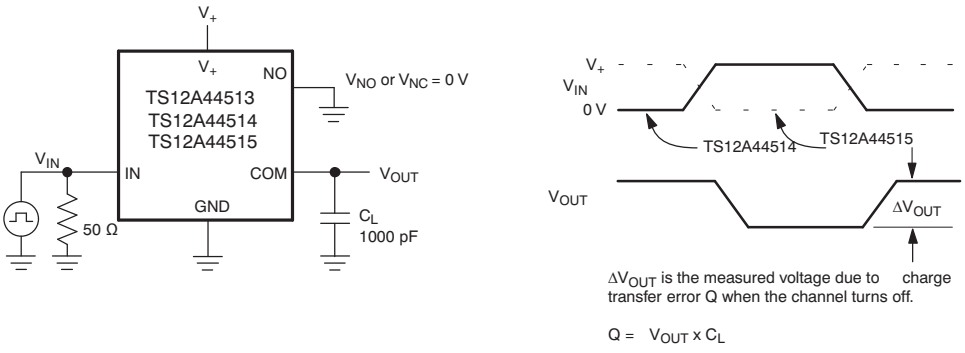

Figure 5. Charge Injection

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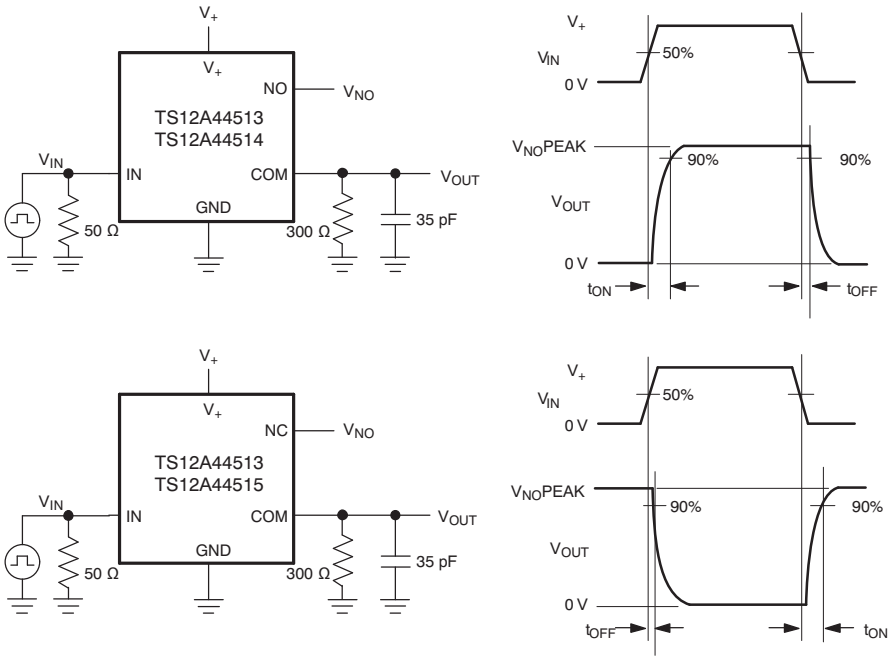
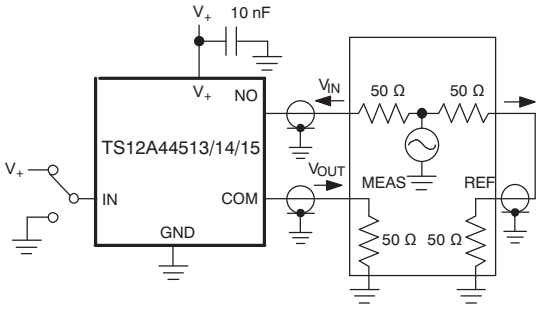


Figure 6. Switching Times



Measurements are standardized against short at socket terminals. OFF isolation is measured between COM and OFF terminals on each switch. ON loss is measured between COM and ON terminals on each switch. Signal direction through switch is reversed; worst values are recorded.

$$\text{OFF Isolation} = 20\log\frac{V_{OUT}}{V_{IN}}$$

$$\text{ON Loss} = 20\log\frac{V_{OUT}}{V_{IN}}$$

Figure 7. OFF Isolation and ON Loss

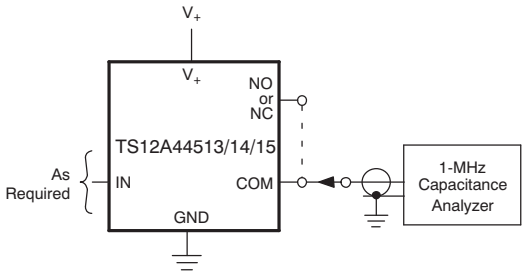


Figure 8. NO, NC, and COM Capacitance

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TS12A44513DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44513	Samples
TS12A44513DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44513	Samples
TS12A44513PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4513	Samples
TS12A44513PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4513	Samples
TS12A44514DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44514	Samples
TS12A44514DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44514	Samples
TS12A44514PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4514	Samples
TS12A44514PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4514	Samples
TS12A44515DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44515	Samples
TS12A44515DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TS12A44515	Samples
TS12A44515PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4515	Samples
TS12A44515PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YD4515	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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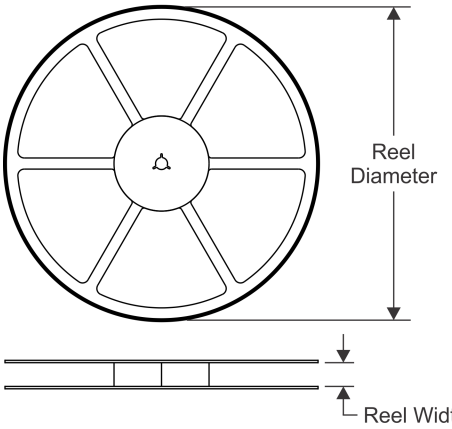
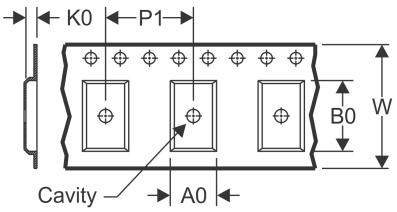
TAPE AND REEL INFORMATION

REEL DIMENSIONS

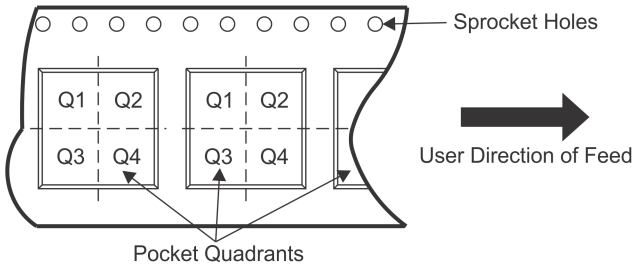


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

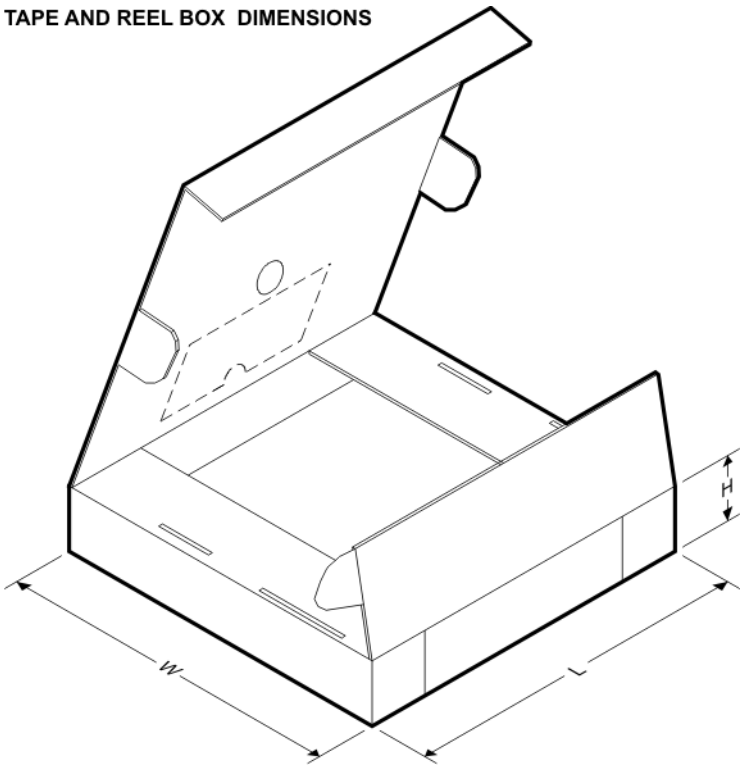
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS12A44513DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TS12A44513PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TS12A44514DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TS12A44514PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TS12A44515DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TS12A44515PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

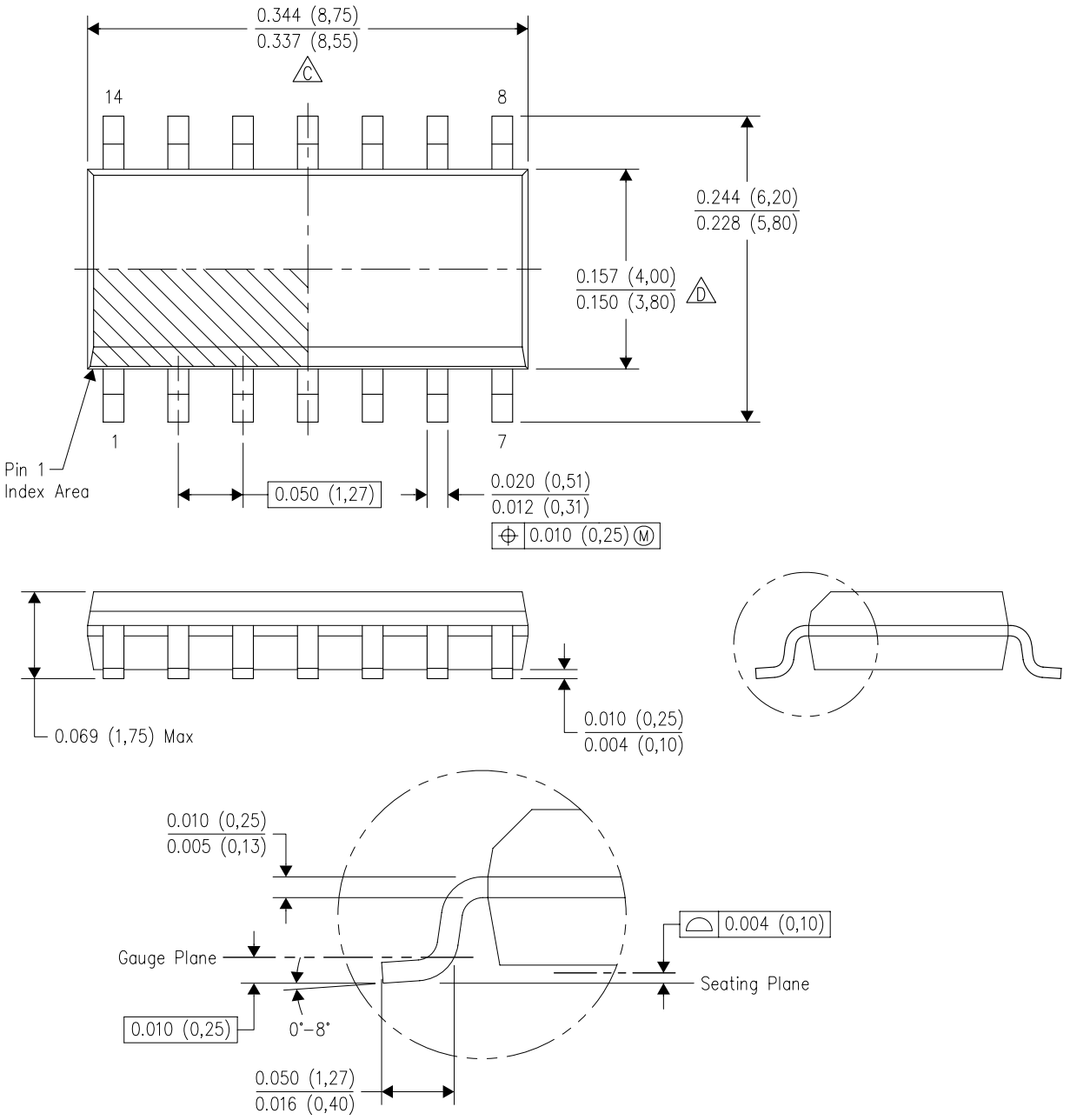
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS12A44513DR	SOIC	D	14	2500	367.0	367.0	38.0
TS12A44513PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TS12A44514DR	SOIC	D	14	2500	367.0	367.0	38.0
TS12A44514PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TS12A44515DR	SOIC	D	14	2500	367.0	367.0	38.0
TS12A44515PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

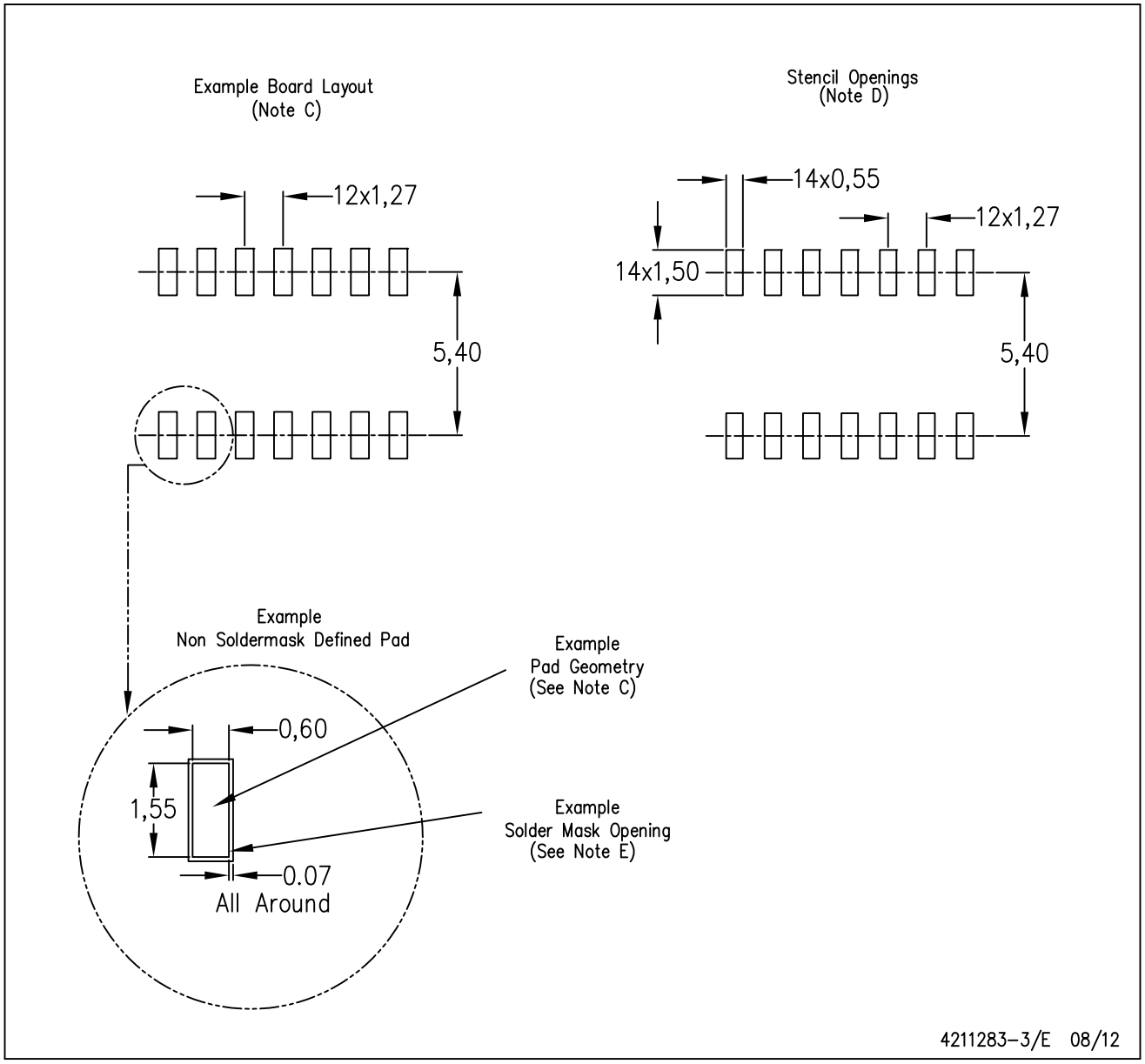
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

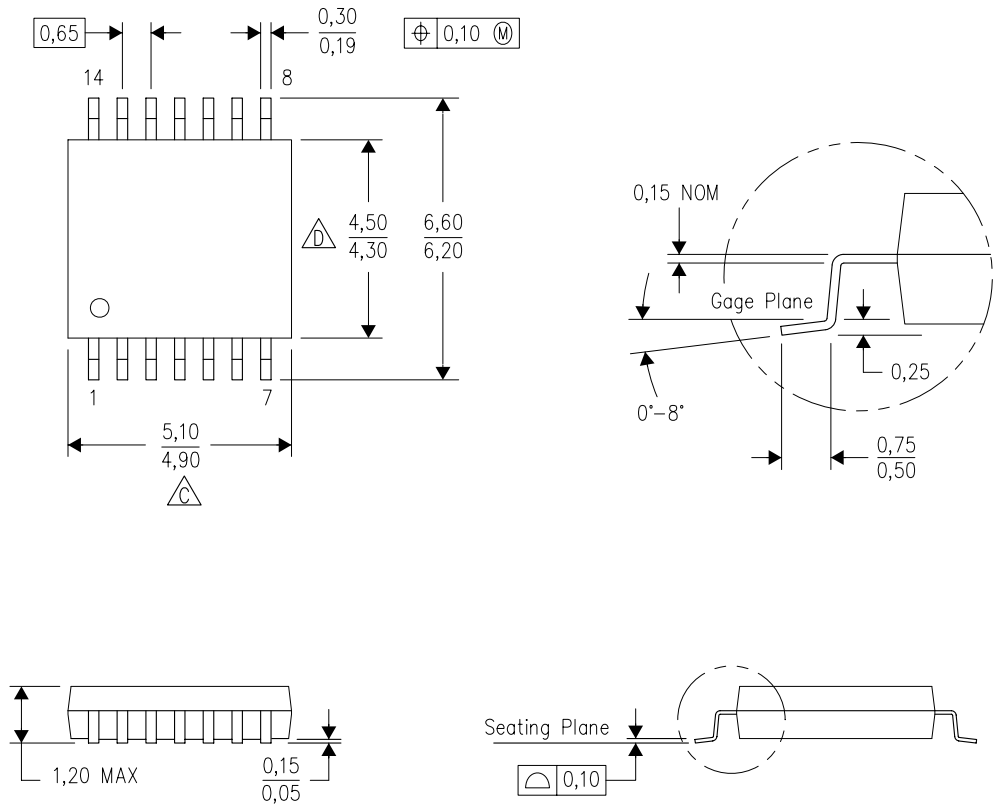
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

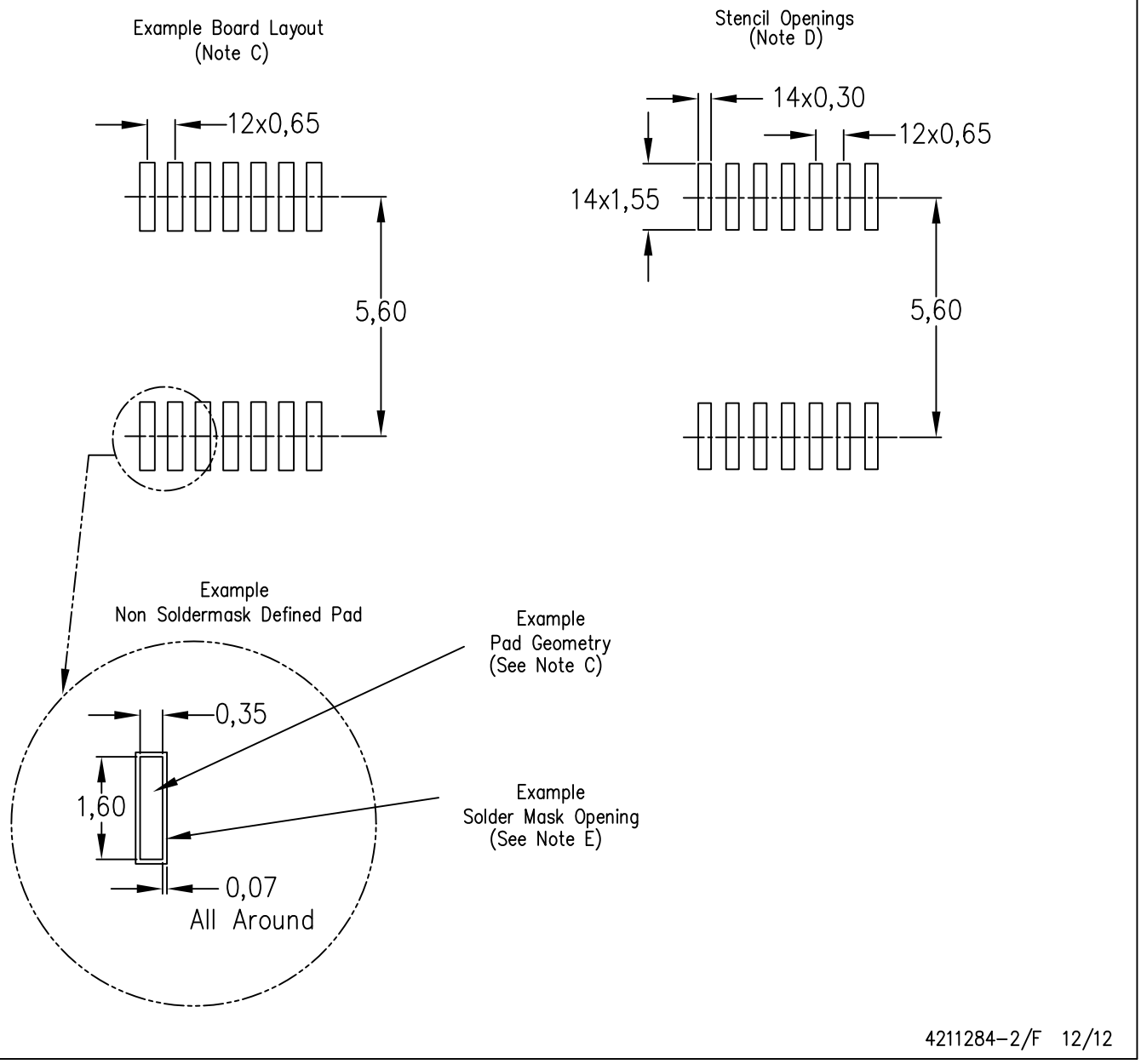
PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040064–3/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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